



Material Content Data Sheet



Sales Product Name		ITD50N04S4L-07		Issued		29. August 2013		
MA#		MA001116614						
Package		PG-TO252-5-11		Weight*		355.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.029	0.57	0.57	5701	5701
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		575	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.38	57.46	573868	574615
wire	non noble metal	aluminium	7429-90-5	4.229	1.19	1.19	11883	11883
encapsulation	organic material	carbon black	1333-86-4	1.380	0.39		3878	
	plastics	epoxy resin	-	24.151	6.79		67858	
	inorganic material	silicondioxide	60676-86-0	112.475	31.60	38.78	316026	387762
leadfinish	non noble metal	tin	7440-31-5	5.072	1.43	1.43	14252	14252
plating	non noble metal	nickel	7440-02-0	0.076	0.02		214	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	215
solder	noble metal	silver	7440-22-4	0.050	0.01		139	
	non noble metal	tin	7440-31-5	0.040	0.01		111	
	non noble metal	lead	7439-92-1	1.894	0.53	0.55	5322	5572
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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